

Amendments to the claims:

This listing of the claims will replace all prior versions and listings of the claims in the application:

Listing of Claims:

1. (Previously Presented) A device comprising an electrical circuit carried by a plastic carrier element, the electrical circuit comprising an electrically conductive thin-film or multi-layer ceramic structure on a surface of the carrier element, wherein one or more further components of the electrical circuit that are electrically coupled to the thin-film or multi-layer ceramic structure are arranged on a side of the electrically conductive thin-film or multi-layer ceramic structure facing the carrier element and wherein the carrier element is at least partially positioned between the one or more further components and the electrically conductive thin-film or multi-layer ceramic structure.
2. (Canceled).
3. (Previously Presented) A device according to claim 1, wherein the components of the electrical circuit arranged on the side of the electrically conductive structure facing the carrier element are at least partly embedded in the carrier element.
4. (Original) A device according to claim 1, wherein the electrically conductive structure comprises a single-layer.
5. (Original) A device according to claim 1, wherein the electrically conductive structure comprises a single-layer or multi-layer thick-film structure.
6. (Original) A device according to claim 1, wherein the electrically conductive structure comprises one or more single-layer or multi-layer electrically conductive films.
7. (Original) A device according to claim 1, wherein the electrically conductive

structure is arranged and constructed so that it forms passive and/or active electronic components.

8. (Original) A device according to claim 1, wherein the electrically conductive structure is arranged and constructed so that it forms strip conductors connecting specific points on the surface of the carrier element with one another.

9. (Previously Presented) A device according to claim 1, wherein components of the electrical circuit are also arranged on a side of the electrically conductive structure remote from the carrier element, said components on the side of the electrically conductive structure remote from the carrier element being adhesively secured or soldered on said structure.

10. (Previously Presented) A device according to claim 1, wherein the components of the electrical circuit arranged on the side of the electrically conductive structure facing the carrier element comprise active or passive components.

11. (Previously Presented) A device according to claim 1, wherein the components of the electrical circuit arranged on the side of the electrically conductive structure facing the carrier element comprise one or more connecting devices for electrical connection of the arrangement to other components of the system containing the arrangement.

12. (Original) A device according to claim 11, wherein the connecting devices comprise one or more contact elements suitable for soldering the arrangement onto an electrical printed circuit board.

13. (Previously Presented) A device according to claim 1, wherein the components of the electrical circuit arranged on the side of the electrically conductive structure facing the carrier element are elements designed for surface mounting.

14. (Previously Presented) A method for manufacture of a device having an

electrical circuit carried by a carrier element and having an electrically conductive structure provided on a surface of the carrier element as a component of the electrical circuit, the method comprising the steps of:

- a) applying the electrically conductive structure to a side of a temporary substrate,
- b) mounting further components of the electrical circuit on the electrically conductive structure the further components being positioned on a side of the electrically conductive structure opposite from the temporary substrate,
- c) applying a composition to the side of the temporary substrate, having the applied electrically conductive structure, at least a portion of the further components extending through the composition,
- d) hardening the applied composition to form the carrier element, and
- e) removing the temporary substrate.

15. (Previously Presented) A method according to claim 4, wherein applying the electrically conductive structure to the side of the temporary substrate comprises applying a single-layer or multi-layer thin-film structure to the temporary structure.

16. (Previously Presented) A method according to claim 14, wherein applying the electrically conductive structure to the side of the temporary substrate comprises applying a single-layer or multi-layer thick-film structure to the temporary substrate.

17. (Previously Presented) A method according to claim 14, wherein applying the electrically conductive structure to the side of the temporary substrate comprises applying one or more single-layer or multi-layer electrically conductive films to the temporary substrate.

18. (Previously Presented) A method according to claim 14, wherein applying the electrically conductive structure to the side of the temporary substrate is effected such that the layer structure of the electrically conductive structure is opposite to the layer structure of the electrically conductive structure present in the finished arrangement on the carrier element.

19. (Original) A method according to claim 14, wherein mounting further components of the electrical circuit on the electrically conductive structure is effected by adhesion or soldering.

20. (Previously Presented) A method according to claim 14, wherein applying the composition forming the carrier element is effected by casting or injection-moulding plastics material at least partly around the further components of the electrical circuit.

21. (Original) A method according to claim 14, wherein removing the temporary substrate is effected by etching away of the same.

22. (Previously Presented) A method according to claim 14, wherein after removing the temporary substrate additional components of the electrical circuit are mounted on a side of the electrically conductive structure remote from the carrier element.

23. (Previously Presented) The device of Claim 9 wherein the components on the side of the electrically conductive structure remote from the carrier element are adhesively secured or soldered on the electrically conductive structure.

24. (Previously Presented) The device of Claim 10 wherein the active or passive components comprise at least one semiconductor chip.

25. (Previously Presented) The device of Claim 11 wherein the connecting devices comprise at least one electrical connector.

26. (Previously Presented) The device of Claim 13 wherein the elements designed for surface mounting are soldered or adhesively secured to the side of the electrically conductive structure facing the carrier element.

27. (New) A device according to Claim 1, wherein the plastic carrier element has a thickness of from about 1mm to about 2 mm.

28. (New) A device according to Claim 1, wherein the further components comprise surface mount (SMT) components, pins, resistors, capacitors, coils, transistors, and/or semiconductor chips.

29. (New) A device according to Claim 1, wherein the plastic carrier element has a thickness of from about 1mm to about 2 mm and wherein the further components comprise surface mount (SMT) components, pins, resistors, capacitors, coils, transistors, and/or semiconductor chips.